

74ALVT16373

16-bit transparent D-type latch; 3-state

Rev. 4 — 2 February 2018

Product data sheet

1 General description

The 74ALVT16373 is a high-performance BiCMOS product designed for V_{CC} operation at 2.5 V or 3.3 V with I/O compatibility up to 5 V.

This device is a 16-bit transparent D-type latch with non-inverting 3-state bus compatible outputs. The device can be used as two 8-bit latches or one 16-bit latch. When latch enable (nLE) input is HIGH, the nQn outputs follow the data (nDn) inputs. When latch enable is taken LOW, the nQn outputs are latched at the levels of the D inputs one setup time prior to the HIGH-to-LOW transition.

2 Features and benefits

- 16-bit transparent latch
- 5 V I/O compatible
- 3-state buffers
- Output capability: +64 mA/-32 mA
- TTL input and output switching levels
- Input and output interface capability to systems at 5 V supply
- Bus-hold data inputs eliminate the need for external pull-up resistors to hold unused inputs
- Live insertion/extraction permitted
- Power-up reset
- Power-up 3-State
- No bus current loading when output is tied to 5 V bus
- Latch-up protection:
 - JESD 17: exceeds 500 mA
- ESD protection:
 - MIL STD 883 method 3015: exceeds 2000 V
 - MM exceeds 200 V

3 Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74ALVT16373DL	-40 °C to +85 °C	SSOP48	plastic shrink small outline package; 48 leads; body width 7.5 mm	SOT370-1
74ALVT16373DGG	-40 °C to +85 °C	TSSOP48	plastic thin shrink small outline package; 48 leads; body width 6.1 mm	SOT362-1

nexperia

4 Functional diagram

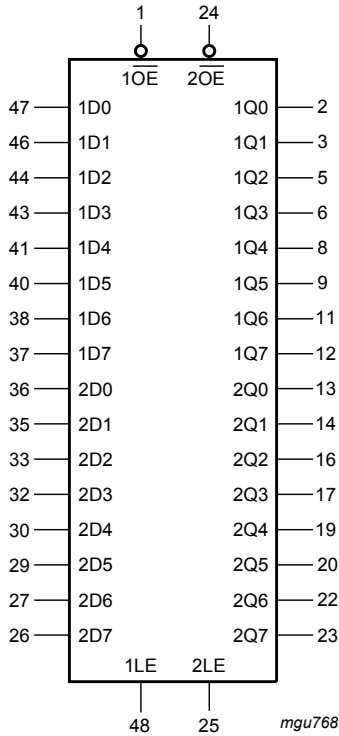


Figure 1. Logic symbol

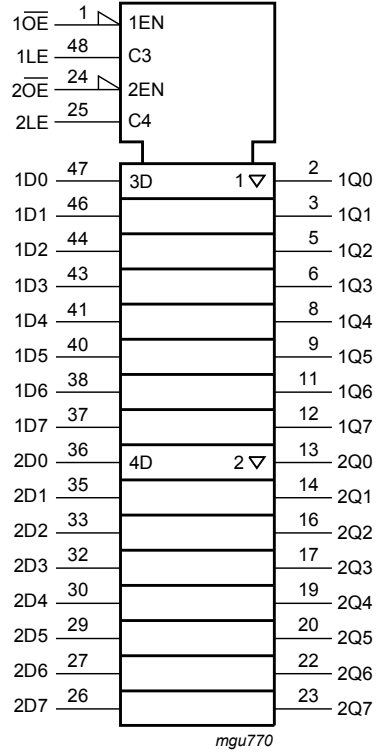


Figure 2. IEC logic symbol

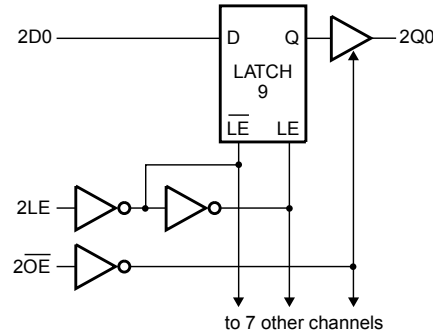
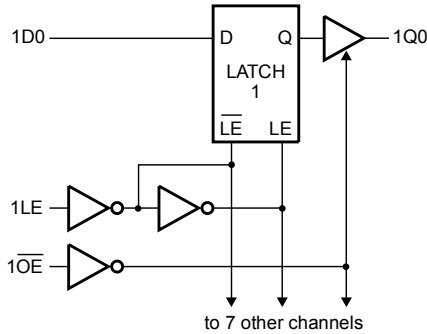


Figure 3. Logic diagram

5 Pinning information

5.1 Pinning

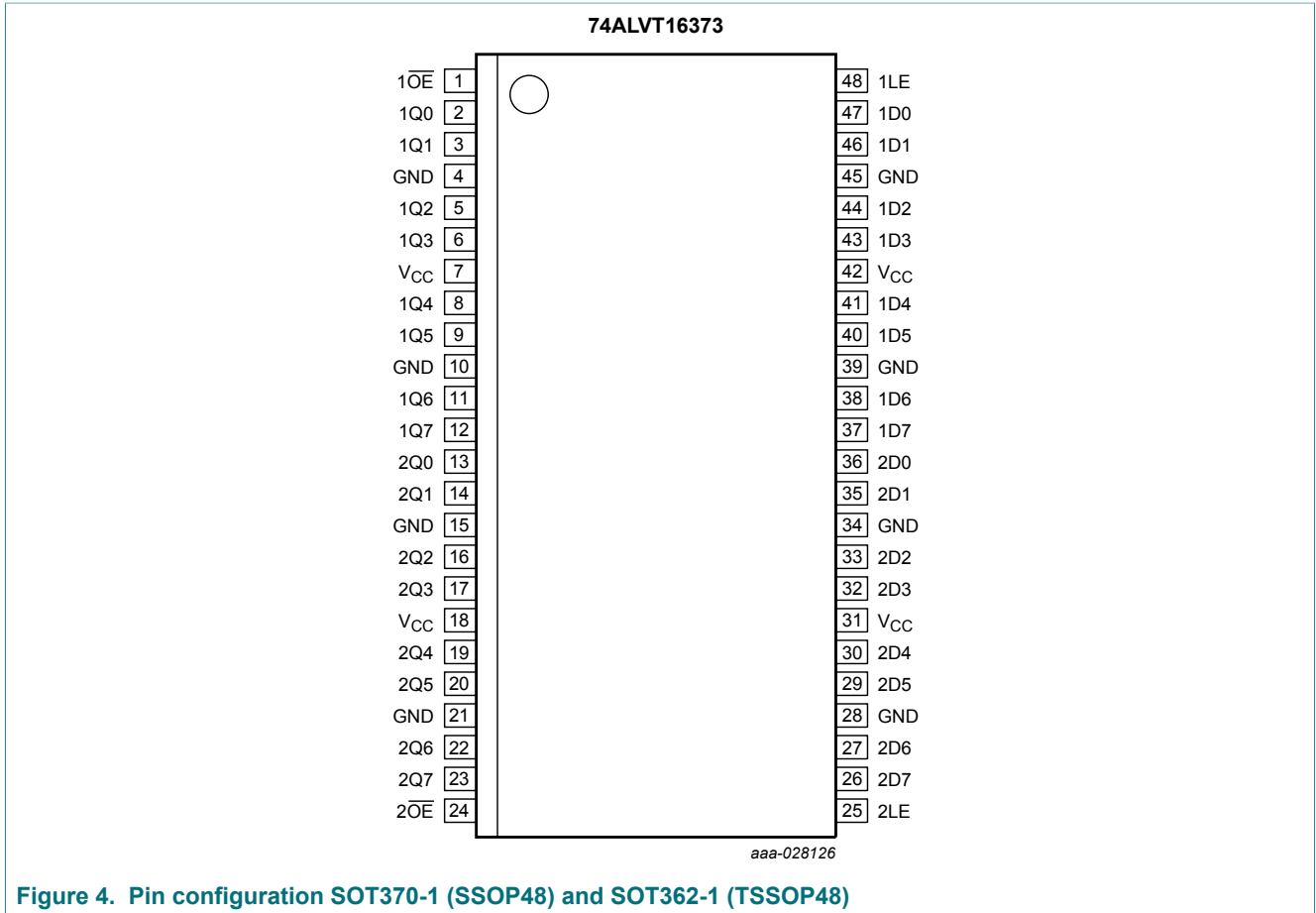


Figure 4. Pin configuration SOT370-1 (SSOP48) and SOT362-1 (TSSOP48)

5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
1D0, 1D1, 1D2, 1D3, 1D4, 1D5, 1D6, 1D7	47, 46, 44, 43, 41, 40, 38, 37	data inputs
2D0, 2D1, 2D2, 2D3, 2D4, 2D5, 2D6, 2D7	36, 35, 33, 32, 30, 29, 27, 26	data inputs
1Q0, 1Q1, 1Q2, 1Q3, 1Q4, 1Q5, 1Q6, 1Q7	2, 3, 5, 6, 8, 9, 11, 12	data outputs
2Q0, 2Q1, 2Q2, 2Q3, 2Q4, 2Q5, 2Q6, 2Q7	13, 14, 16, 17, 19, 20, 22, 23	data outputs
1OE, 2OE	1, 24	output enable inputs (active LOW)
1LE, 2LE	48, 25	latch enable inputs (active HIGH)
GND	4, 10, 15, 21, 28, 34, 39, 45	ground (0 V)
VCC	7, 18, 31, 42	supply voltage

6 Functional description

Table 3. Function table ^[1]

Operating mode	Inputs			Internal latches	Outputs nQn
	n \overline{OE}	nLE	nDn		
enable and read register (transparent mode)	L	H	L	L	L
	L	H	H	H	H
latch and read register	L	↓	l	L	L
	L	↓	h	H	H
Hold	L	L	X	NC	NC
Latch register and disable outputs	H	L	X	NC	Z
	H	H	nDn	nDn	Z

- [1] H = HIGH voltage level;
 L = LOW voltage level;
 ↓ = HIGH-to-LOW LE transition;
 h = HIGH voltage level one set-up time prior to the HIGH-to-LOW LE transition;
 l = LOW voltage level one set-up time prior to the HIGH-to-LOW LE transition;
 X = don't care;
 NC = No change;
 Z = high-impedance OFF-state.

7 Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage		-0.5	+4.6	V
V _I	input voltage		^[1] -0.5	+7.0	V
V _O	output voltage	output in OFF-state or HIGH-state	^[1] -0.5	+7.0	V
I _{IK}	input clamping current	V _I < 0 V	-50	-	mA
I _{OK}	output clamping current	V _O < 0 V	-50	-	mA
I _O	output current	output in LOW-state	-	128	mA
		output in HIGH-state	-64	-	mA
T _{stg}	storage temperature		-65	+150	°C
T _j	junction temperature		^[2] -	+150	°C

- [1] The input and output negative voltage ratings may be exceeded if the input and output clamp current ratings are observed.
 [2] The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability.

8 Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		Unit
			Min	Max	Min	Max	
V_{CC}	supply voltage		2.3	2.7	3.0	3.6	V
V_I	input voltage		0	5.5	0	5.5	V
I_{OH}	HIGH-level output current		-	-8	-	-32	mA
I_{OL}	LOW-level output current	none	-	8	-	32	mA
		current duty cycle $\leq 50\%$; $f_i \geq 1\text{ kHz}$	-	24	-	64	mA
$\Delta t/\Delta V$	input transition rise and fall rate	outputs enabled	-	10	-	10	ns/V
T_{amb}	ambient temperature	free-air	-40	+85	-40	+85	$^{\circ}\text{C}$

9 Static characteristics

Table 6. Static characteristics

At recommended operating conditions; $T_{amb} = -40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ ^[1]	Max	Unit
$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$						
V_{IK}	input clamping voltage	$V_{CC} = 2.3\text{ V}$; $I_{IK} = -18\text{ mA}$	-	-0.85	-1.2	V
V_{IH}	HIGH-level input voltage		1.7	-	-	V
V_{IL}	LOW-level input voltage		-	-	0.7	V
V_{OH}	HIGH-level output voltage	$V_{CC} = 2.3\text{ V}$ to 2.7 V ; $I_O = -100\text{ }\mu\text{A}$	$V_{CC} - 0.2$	-	-	V
		$V_{CC} = 2.3\text{ V}$; $I_O = -8\text{ mA}$	1.8	-	-	V
V_{OL}	LOW-level output voltage	$V_{CC} = 2.3\text{ V}$; $I_O = 100\text{ }\mu\text{A}$	-	0.07	0.2	V
		$V_{CC} = 2.3\text{ V}$; $I_O = 24\text{ mA}$	-	0.3	0.5	V
$V_{OL(pu)}$	power-up LOW-level output voltage	$V_{CC} = 2.7\text{ V}$; $I_O = 1\text{ mA}$; $V_I = V_{CC}$ or GND	[2]	-	0.55	V
I_I	input leakage current	all input pins	[3]			
		$V_{CC} = 0\text{ V}$ or 2.7 V ; $V_I = 5.5\text{ V}$	-	0.1	10	μA
		control pins				
		$V_{CC} = 2.7\text{ V}$; $V_I = V_{CC}$ or GND	-	0.1	± 1	μA
		data pins;	[3]			
		$V_{CC} = 2.7\text{ V}$; $V_I = V_{CC}$	-	0.1	1	μA
	$V_{CC} = 2.7\text{ V}$; $V_I = 0\text{ V}$	-	0.1	-5	μA	
I_{OFF}	power-off leakage current	$V_{CC} = 0\text{ V}$; V_I or $V_O = 0\text{ V}$ to 4.5 V	-	0.1	± 100	μA
I_{BHL}	bus hold LOW current	data inputs; $V_{CC} = 2.3\text{ V}$; $V_I = 0.7\text{ V}$	[4]	90	-	μA
I_{BHH}	bus hold HIGH current	data inputs; $V_{CC} = 2.3\text{ V}$; $V_I = 1.7\text{ V}$	[4]	-10	-	μA
I_{EX}	external current	output in HIGH-state when $V_O > V_{CC}$; $V_O = 5.5\text{ V}$; $V_{CC} = 2.3\text{ V}$	-	10	125	μA

Symbol	Parameter	Conditions	Min	Typ ^[1]	Max	Unit	
$I_{O(pu/pd)}$	power-up/power-down output current	$V_{CC} \leq 1.2 \text{ V}$; $V_O = 0.5 \text{ V to } V_{CC}$; $V_I = \text{GND or } V_{CC}$; $n\overline{OE} = \text{don't care}$ ^[5]	-	1	100	μA	
I_{OZ}	OFF-state output current	$V_{CC} = 2.7 \text{ V}$; $V_I = V_{IL} \text{ or } V_{IH}$					
		output HIGH: $V_O = 2.3 \text{ V}$	-	0.5	5	μA	
		output LOW: $V_O = 0.5 \text{ V}$	-	0.5	-5	μA	
I_{CC}	supply current	$V_{CC} = 2.7 \text{ V}$; $V_I = \text{GND or } V_{CC}$; $I_O = 0 \text{ A}$					
		outputs HIGH	-	0.04	0.1	mA	
		outputs LOW	-	2.3	4.5	mA	
		outputs disabled ^[6]	-	0.04	0.1	mA	
ΔI_{CC}	additional supply current	per input pin; $V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$; one input at $V_{CC} - 0.6 \text{ V}$; other inputs at $V_{CC} \text{ or } \text{GND}$ ^[7]	-	0.04	0.4	mA	
C_I	input capacitance	$V_I = 0 \text{ V or } V_{CC}$	-	3	-	pF	
C_O	output capacitance	Outputs disabled; $V_O = 0 \text{ V or } 3 \text{ V}$	-	9	-	pF	
$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$							
V_{IK}	input clamping voltage	$V_{CC} = 3.0 \text{ V}$; $I_{IK} = -18 \text{ mA}$	-	-0.85	-1.2	V	
V_{IH}	HIGH-level input voltage		2.0	-	-	V	
V_{IL}	LOW-level input voltage		-	-	0.8	V	
V_{OH}	HIGH-level output voltage	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$; $I_O = -100 \mu\text{A}$	$V_{CC} - 0.2$	V_{CC}	-	V	
		$V_{CC} = 3.0 \text{ V}$; $I_O = -32 \text{ mA}$	2.0	2.3	-	V	
V_{OL}	LOW-level output voltage	$V_{CC} = 3.0 \text{ V}$; $I_O = 100 \mu\text{A}$	-	0.07	0.2	V	
		$V_{CC} = 3.0 \text{ V}$; $I_O = 16 \text{ mA}$	-	0.25	0.4	V	
		$V_{CC} = 3.0 \text{ V}$; $I_O = 32 \text{ mA}$	-	0.3	0.5	V	
		$V_{CC} = 3.0 \text{ V}$; $I_O = 64 \text{ mA}$	-	0.4	0.55	V	
$V_{OL(pu)}$	power-up LOW-level output voltage	$V_{CC} = 3.6 \text{ V}$; $I_O = 1 \text{ mA}$; $V_I = V_{CC} \text{ or } \text{GND}$ ^[2]	-	-	0.55	V	
I_I	input leakage current	all input pins ^[3]					
		$V_{CC} = 0 \text{ V or } 3.6 \text{ V}$; $V_I = 5.5 \text{ V}$	-	0.1	10	μA	
		control pins					
		$V_{CC} = 3.6 \text{ V}$; $V_I = V_{CC} \text{ or } \text{GND}$	-	0.1	± 1	μA	
		data pins ^[3]					
		$V_{CC} = 3.6 \text{ V}$; $V_I = V_{CC}$	-	0.5	1	μA	
	$V_{CC} = 3.6 \text{ V}$; $V_I = 0 \text{ V}$	-	0.1	-5	μA		
I_{OFF}	power-off leakage current	$V_{CC} = 0 \text{ V}$; $V_I \text{ or } V_O = 0 \text{ V to } 4.5 \text{ V}$	-	0.1	± 100	μA	
I_{BHL}	bus hold LOW current	data inputs; $V_{CC} = 3 \text{ V}$; $V_I = 0.8 \text{ V}$	75	130	-	μA	
I_{BHH}	bus hold HIGH current	data inputs; $V_{CC} = 3 \text{ V}$; $V_I = 2.0 \text{ V}$	-75	-140	-	μA	
I_{BHLO}	bus hold LOW overdrive current	data inputs; $V_{CC} = 3.6 \text{ V}$; $V_I = 0 \text{ V to } 3.6 \text{ V}$ ^[8]	500	-	-	μA	
I_{BHHO}	bus hold HIGH overdrive current	data inputs; $V_{CC} = 3.6 \text{ V}$; $V_I = 0 \text{ V to } 3.6 \text{ V}$ ^[8]	-500	-	-	μA	

Symbol	Parameter	Conditions	Min	Typ ^[1]	Max	Unit
I _{EX}	external current	output in HIGH-state when V _O > V _{CC} ; V _O = 5.5 V; V _{CC} = 3.0 V	-	10	125	μA
I _{O(pu/pd)}	power-up/power-down output current	V _{CC} ≤ 1.2 V; V _O = 0.5 V to V _{CC} ; V _I = GND or V _{CC} ; n \overline{OE} = don't care ^[9]	-	1	±100	μA
I _{OZ}	OFF-state output current	V _{CC} = 3.6 V; V _I = V _{IL} or V _{IH}				
		output HIGH: V _O = 3.0V	-	0.5	5	μA
		output LOW: V _O = 0.5 V	-	0.5	-5	μA
I _{CC}	supply current	V _{CC} = 3.6 V; V _I = GND or V _{CC} ; I _O = 0 A				
		outputs HIGH	-	0.04	0.1	mA
		outputs LOW	-	3.5	5	mA
		outputs disabled ^[6]	-	0.05	0.1	mA
ΔI _{CC}	additional supply current	per input pin; V _{CC} = 3 V to 3.6 V; one input at V _{CC} - 0.6 V; other inputs at V _{CC} or GND ^[7]	-	0.04	0.4	mA
C _I	input capacitance	V _I = 0 V or V _{CC}	-	3	-	pF
C _O	output capacitance	output disabled; V _O = 0 V or 3 V	-	9	-	pF

[1] All typical values for V_{CC} = 2.5 V ± 0.2 V are measured at V_{CC} = 2.5 V and T_{amb} = 25 °C.

All typical values for V_{CC} = 3.3 V ± 0.3 V are measured at V_{CC} = 3.3 V and T_{amb} = 25 °C.

[2] For valid test results, data must not be loaded into the latches after applying power.

[3] Unused pins at V_{CC} or GND.

[4] Not guaranteed.

[5] This parameter is valid for any V_{CC} between 0 V and 1.2 V with a transition time of up to 10 ms.

From V_{CC} = 1.2 V to V_{CC} = 2.5 V ± 0.2 V a transition time of 100 μs is permitted. This parameter is valid for T_{amb} = 25 °C only.

[6] I_{CC} with outputs disabled is measured with outputs pulled to V_{CC} or GND.

[7] This is the increase in supply current for each input at the specified voltage level other than V_{CC} or GND.

[8] This is the bus hold overdrive current required to force the input to the opposite logic state.

[9] This parameter is valid for any V_{CC} between 0 V and 1.2 V with a transition time of up to 10 ms.

From V_{CC} = 1.2 V to V_{CC} = 3.3 V ± 0.3 V a transition time of 100 μs is permitted. This parameter is valid for T_{amb} = 25 °C only.

10 Dynamic characteristics

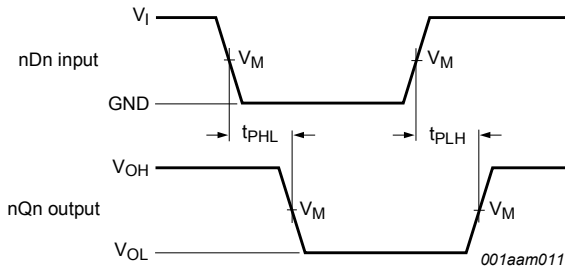
Table 7. Dynamic characteristics

At recommended operating conditions; $T_{amb} = -40\text{ °C}$ to $+85\text{ °C}$; voltages are referenced to GND (ground = 0 V); for test circuit see [Figure 9](#).

Symbol	Parameter	Conditions	Min	Typ ^[1]	Max	Unit
$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$						
t_{PLH}	LOW to HIGH propagation delay	nDn to nQn; see Figure 5	1.0	2.0	3.2	ns
t_{PHL}	HIGH to LOW propagation delay	nDn to nQn; see Figure 5	1.0	2.4	4.2	ns
t_{PLH}	LOW to HIGH propagation delay	nLE to nQn; see Figure 6	1.5	2.6	4.2	ns
t_{PHL}	HIGH to LOW propagation delay	nLE to nQn; see Figure 6	1.5	2.8	4.5	ns
t_{PZH}	OFF-state to HIGH propagation delay	\overline{nOE} to nQn; see Figure 7	2.0	3.5	5.5	ns
t_{PZL}	OFF-state to LOW propagation delay	\overline{nOE} to nQn; see Figure 7	1.5	2.6	4.7	ns
t_{PHZ}	HIGH to OFF-state propagation delay	\overline{nOE} to nQn; see Figure 7	1.5	2.7	4.5	ns
t_{PLZ}	LOW to OFF-state propagation delay	\overline{nOE} to nQn; see Figure 7	1.0	2.0	3.5	ns
$t_{su(H)}$	set-up time HIGH	nDn to nLE; see Figure 8	0	-0.7	-	ns
$t_{su(L)}$	set-up time LOW	nDn to nLE; see Figure 8	1.5	0.2	-	ns
$t_{h(H)}$	hold time HIGH	nDn to nLE; see Figure 8	0.5	-0.2	-	ns
$t_{h(L)}$	hold time LOW	nDn to nLE; see Figure 8	1.5	0.7	-	ns
t_{WH}	pulse width HIGH	nLE; see Figure 6	1.5	-	-	ns
$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$						
t_{PLH}	LOW to HIGH propagation delay	nDn to nQn; see Figure 5	0.5	1.6	2.5	ns
t_{PHL}	HIGH to LOW propagation delay	nDn to nQn; see Figure 5	0.5	1.8	2.9	ns
t_{PLH}	LOW to HIGH propagation delay	nLE to nQn; see Figure 6	1.0	2.0	3.1	ns
t_{PHL}	HIGH to LOW propagation delay	nLE to nQn; see Figure 6	1.0	2.3	3.3	ns
t_{PZH}	OFF-state to HIGH propagation delay	\overline{nOE} to nQn; see Figure 7	1.5	2.3	4.0	ns
t_{PZL}	OFF-state to LOW propagation delay	\overline{nOE} to nQn; see Figure 7	1.0	1.9	3.1	ns
t_{PHZ}	HIGH to OFF-state propagation delay	\overline{nOE} to nQn; see Figure 7	1.5	2.9	4.5	ns
t_{PLZ}	LOW to OFF-state propagation delay	\overline{nOE} to nQn; see Figure 7	1.5	2.3	3.7	ns
$t_{su(H)}$	set-up time HIGH	nDn to nLE; see Figure 8	0.5	-0.2	-	ns
$t_{su(L)}$	set-up time LOW	nDn to nLE; see Figure 8	0.8	0.2	-	ns
$t_{h(H)}$	hold time HIGH	nDn to nLE; see Figure 8	0.8	0	-	ns
$t_{h(L)}$	hold time LOW	nDn to nLE; see Figure 8	1.0	0.2	-	ns
t_{WH}	pulse width HIGH	nLE; see Figure 6	1.5	-	-	ns

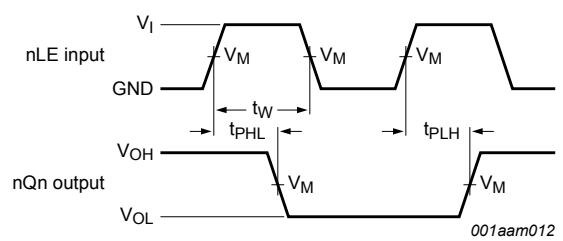
[1] All typical values for $V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$ are measured at $V_{CC} = 2.5\text{ V}$ and $T_{amb} = 25\text{ °C}$.
All typical values for $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ are measured at $V_{CC} = 3.3\text{ V}$ and $T_{amb} = 25\text{ °C}$.

10.1 Waveforms and test circuit



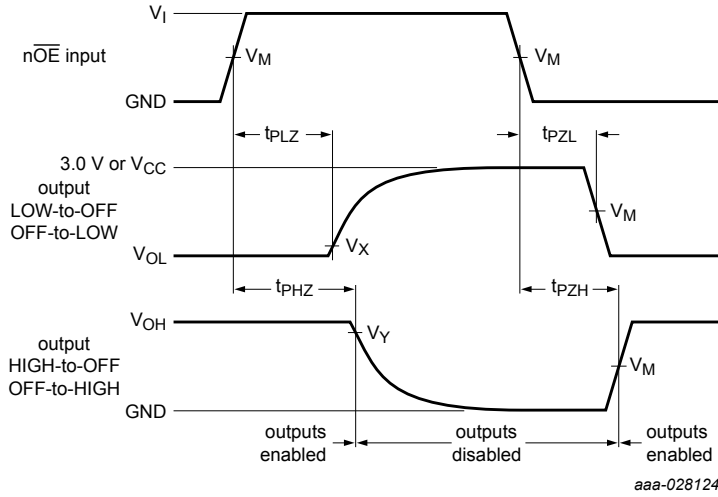
Measurement points are given in [Table 8](#). V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Figure 5. Input (nDn) to output (nQn) propagation delays



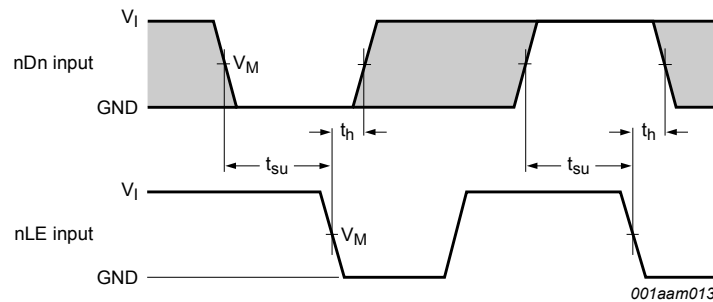
Measurement points are given in [Table 8](#). V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Figure 6. Latch enable input (nLE) to data output (nQn) propagation delays and pulse width



Measurement points are given in [Table 8](#). V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Figure 7. OFF-state to HIGH or LOW and HIGH or LOW to OFF-state propagation delays



Measurement points are given in [Table 8](#). V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Figure 8. Input (nDn) to input (nLE) data set-up and hold times

Table 8. Measurement points

V _{CC}	Input		Output		
	V _I	V _M	V _M	V _X	V _Y
V _{CC} ≤ 2.7 V	V _{CC}	0.5 × V _{CC}	0.5 × V _{CC}	V _{OL} + 0.15 V	V _{OH} - 0.15 V
V _{CC} ≥ 3.0 V	3.0 V	1.5 V	1.5 V	V _{OL} + 0.3 V	V _{OH} - 0.3 V

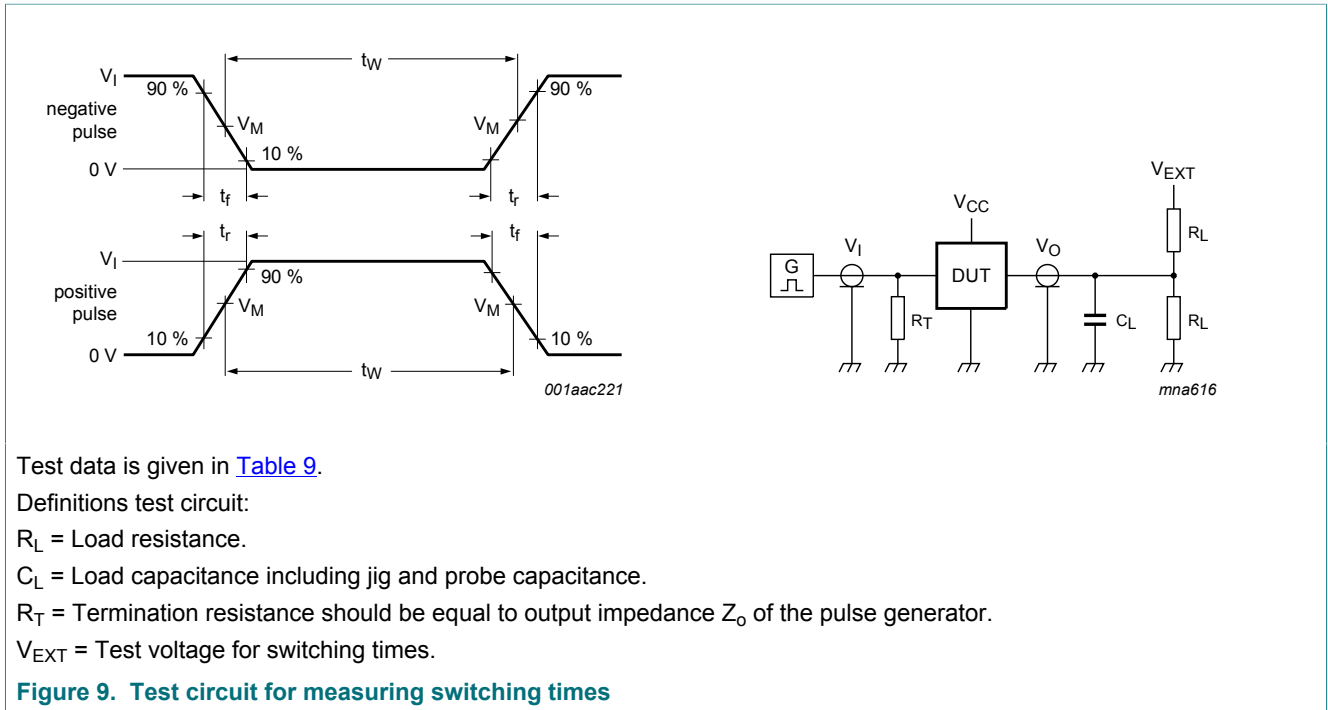


Table 9. Test data

Input		Load				V _{EXT}		
V _I	f _i	t _w	t _r , t _f	C _L	R _L	t _{PHZ} , t _{PZH}	t _{PLZ} , t _{PZL}	t _{PLH} , t _{PHL}
3.0 V or V _{CC} whichever is less	≤ 10 MHz	500 ns	≤ 2.5 ns	50 pF	500 Ω	GND	6 V or V _{CC} × 2	open

11 Package outline

SSOP48: plastic shrink small outline package; 48 leads; body width 7.5 mm

SOT370-1

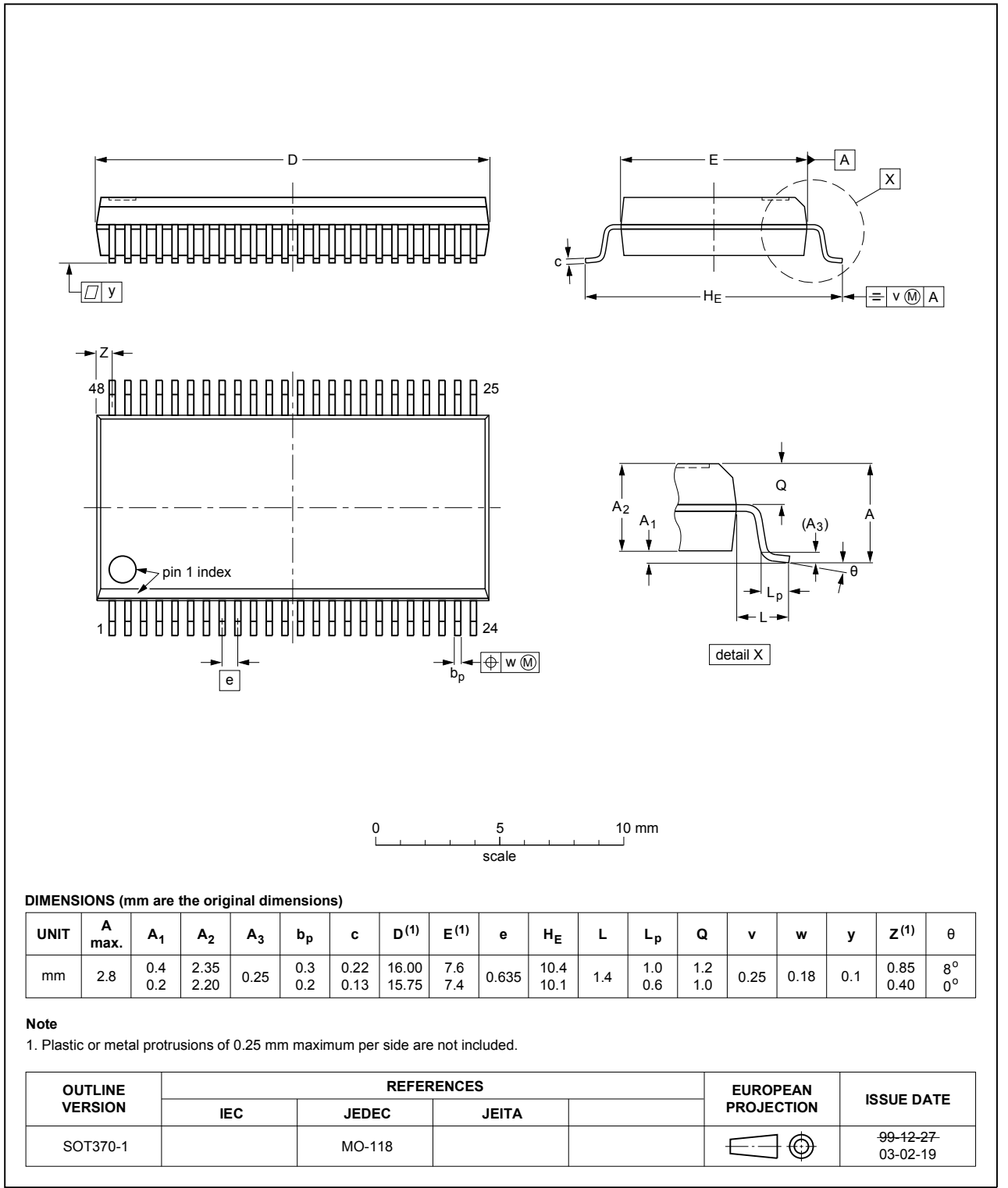
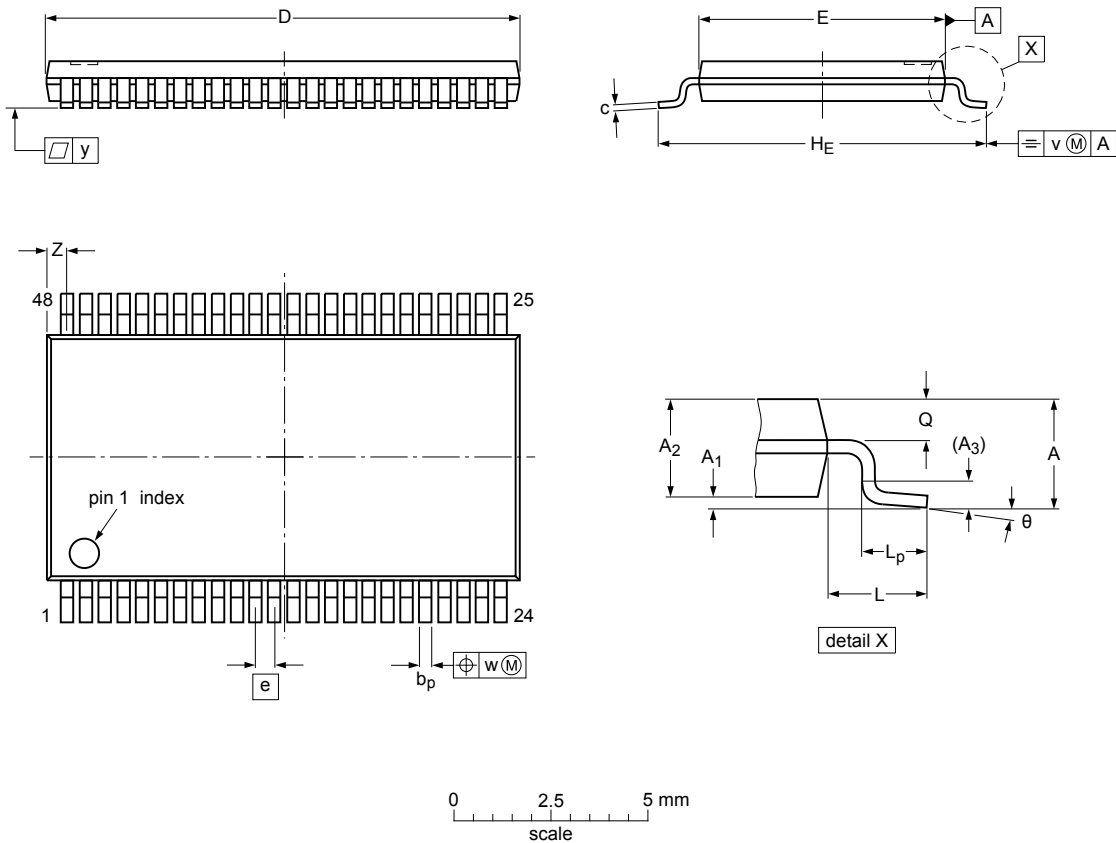


Figure 10. Package outline SOT370-1 (SSOP48)

TSSOP48: plastic thin shrink small outline package; 48 leads; body width 6.1 mm

SOT362-1



Dimensions (mm are the original dimensions)

Unit	A	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽²⁾	e	H _E	L	L _p	Q	v	w	y	Z	θ
max		0.15	1.05		0.28	0.2	12.6	6.2		8.3		0.8	0.50				0.8	8°
nom	1.2			0.25					0.5		1			0.25	0.08	0.1		
min		0.05	0.85		0.17	0.1	12.4	6.0		7.9		0.4	0.35				0.4	0°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

sot362-1_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT362-1		MO-153				03-02-19 13-08-05

Figure 11. Package outline SOT362-1 (TSSOP48)

12 Abbreviations

Table 10. Abbreviations

Acronym	Description
BICMOS	Bipolar Complementary Metal Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
MIL	Military
MM	Machine Model
TTL	Transistor-Transistor Logic

13 Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74ALVT16373 v.4	20180202	Product data sheet	-	74ALVT16373 v.3
Modifications:	<ul style="list-style-type: none"> The format of this data sheet has been redesigned to comply with the identity guidelines of Nexperia. Legal texts have been adapted to the new company name where appropriate. 			
74ALVT16373 v.3	19991018	Product specification	-	74ALVT16373 v.2
74ALVT16373 v.2	19980213	Product specification	-	74ALVT16373 v.1
74ALVT16373 v.1	19960529	Product specification	-	-

14 Legal information

14.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nexperia.com>.

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